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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Christophe MALEVILLE et al.

Confirmation No.5090

Application No.: 10/808,288

Group Art Unit: 2812

Filing Date: March 25, 2004

Examiner: Stanetta D. Isaac

For: METHOD FOR PREPARING A BONDING
SURFACE OF A SEMICONDUCTOR LAYER OF
A WAFER

Atty. Docket No.: 4717-10500

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

In response to the office action dated June 20, 2005, please enter the following amendments and comments into the file of this application.

Amendments to the claims are reflected in the complete listing of all claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.

No fees are believed to be due for the claim changes made in this response. Should any fees be required to process this amendment, however, please charge them to Winston & Strawn LLP Deposit Account No. 50-1814.